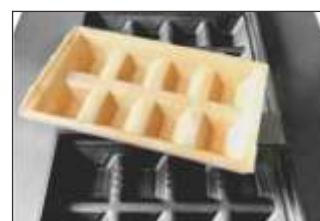


**“RW” - Series
Specialized Wafer Plant**



“Monaka Wafer Tray”



“Oval Shape Design”



'RW' Series Specialized Wafer Plant for Round & Oval Shape

The specialized wafer baking plant RW series is suitable for the production of first class quality wafers discs. These machines can be Equipped with 60 or more baking plates (tongs) according to the required output. The machine is built with a steel frame of rigid construction. An endless chain conveys the baking plates on their carriers through the baking chamber driven by a chain drive infinitely variable in speed through its range.

The standard size of the baking plates is 500 mm x 175 mm. Also, special size of baking plates can be supplied on request. These baking plates can easily be exchanged to produce wafers discs of different designs. The oven are heated by L.P. Gas. The RW Series has an motorized pumping.

Heating (either by liquified petroleum gas)

By Gas : The gas heating system has automatic ignition with safety devices. In the case of gas, air or power failure a automatic cutout device on the heating system will operate. The oven is equipped with special burners. Precise controls for the mixture of gas and air gives high efficiency combustion. On gas heated machines the exterior of baking plates have pyramidal shapes cast-on to give increased surface area and thus better heat exchange.

Baking Plates

The plates are made of special alloy. The selection of alloy and casting procedure ensures dimensional stability, a homogenous and dense surface, thermal stability, good heat accumulation characteristics and excellent thermal conductivity. Special finishing is done to ensure trouble free release of wafer sheets. The wafer disc thickness is quick and easy to adjust.

Drive and Controls

The control panel can be mounted at the discharge end of the oven or at a distance of up to one meter for ease of operation. This provides control for the drive, batter pump, blowers and ignition.

The drive is by an electric motor through a gear box and chain drive protected by an overload safety clutch. Baking time is adjustable between 1.5 and 3 minutes by means of potentiometer on the control panel. Temperature is measured precisely for top & bottom by sensors.

Heating

High Efficiency triangular burners can be adjusted for an extremely even application of heat over the entire surface of the baking plates.

Info System

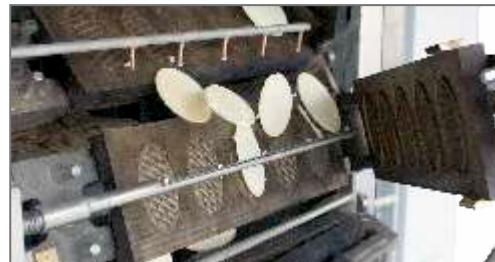
Operator panel includes plate temperature, baking time and other useful function.

Sheet take-off

There is air blowing facility for simple removal of the wafer disc from the baking plates onto a receiving conveyor and transported to the next stage.

Technical Details

TYPE	RW 60
No.of Baking Plates (tongs)	60
Output of wafer Products/Hr*	7500(Approx)**
GAS HEATING*	
L.P.Gas consumption Kgs/hr	15 - 20
Electrical load in Kw	5
DIMENSIONS IN MM	
Length	7000
Width	1430
Height	2100
WEIGHT & SHIPPING DETAILS	
Net Weight in Kg(approx)	8500
Including export packing Kg (approx)	9000
Shipping space in Cubic Meters (approx)	21.0



** Size,Shape & weight will decide the output of the Machine

*Modifications Reserved

We are constantly guided by our principle of offering ourcustomers better and better machines; to give increased efficiency and higher levels of automation. The technical data and illustrations are subject to change without notice

R & D Engineers

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